

# 8310

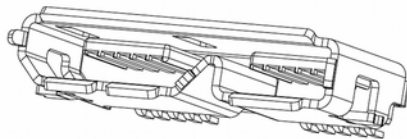
## SMT USB 3.0 Micro-Steckverbinder, Typ B, liegend SMT USB 3.0 Micro Connectors, Type B, Horizontal

### Technische Daten / Technical Data

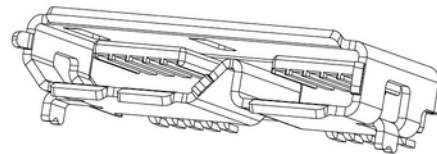
Gehäuse	Stahl verzinkt
Shell	Tin plated steel
Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Oberfläche Lötanschluss	Verzinkt
Plating Solder Side	Tin plated
Lötbarkeit	IEC 60512-12A
Solderability	IEC 60512-12A
Durchgangswiderstand	< 30m $\Omega$ VBUS/GND im Auslieferungszustand < 50m $\Omega$ im Auslieferungszustand
Contact Resistance	< 30m $\Omega$ VBUS/GND initially < 50m $\Omega$ initially
Isolationswiderstand	> 10 <sup>8</sup> $\Omega$
Insulation Resistance	> 10 <sup>8</sup> $\Omega$
Spannungsfestigkeit	100V <sub>AC</sub>
Test Voltage	100V <sub>AC</sub>
Nennspannung	30V <sub>RMS</sub>
Voltage Rating	30V <sub>RMS</sub>
Nennstrom	1,8A VBUS/GND, 0,25A DATA
Current Rating	1.8A VBUS/GND, 0.25A DATA
Temperaturbereich	-30°C ... +85°C
Temperature Range	-30°C ... +85°C
Verarbeitung	Reflow-Lötverfahren
Processing	Reflow soldering



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8310-2-2-80

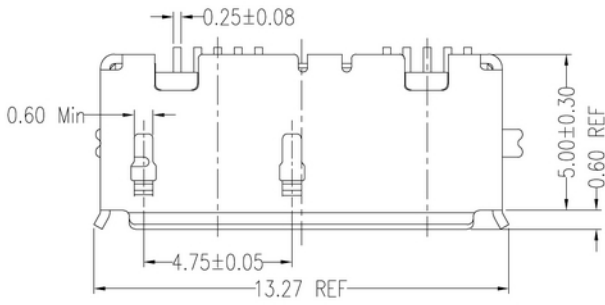


Micro-USB 3.0 Typ B Female

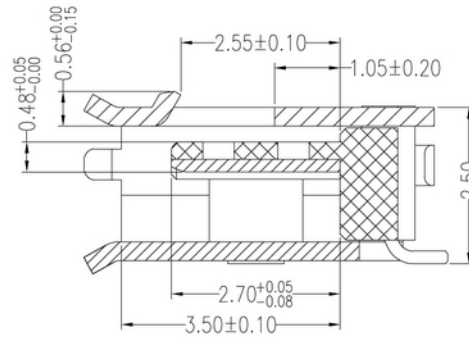
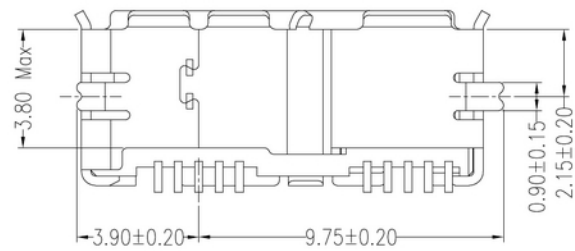
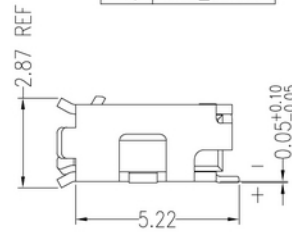
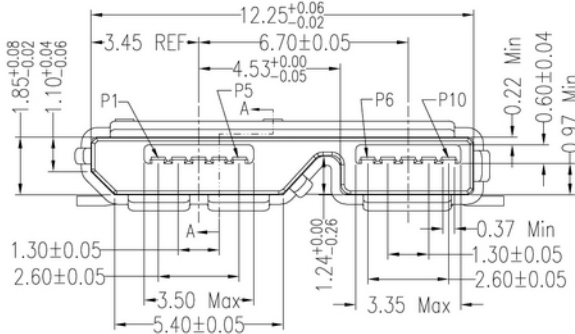
8310-2-5-80

# 8310

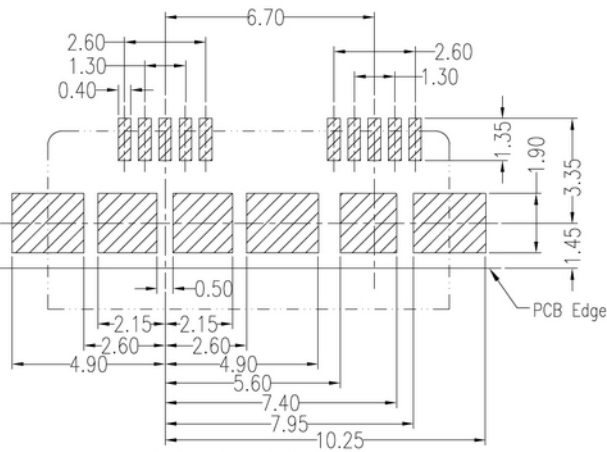
**SMT USB 3.0 Micro-Steckverbinder, Typ B, liegend**  
**SMT USB 3.0 Micro Connectors, Type B, Horizontal**



Pin Number	Signal Name
1	VBUS
2	D-
3	D+
4	ID
5	GND
6	MicB_SSTX-
7	MicB_SSTX+
8	GND_DRAIN
9	MicB_SSRX-
10	MicB_SSRX+



SECTION: A-A  
SCALE: 2:1



RECOMMENDED PCB LAYOUT  
COMPONENT SIDE(Tol:±0.05)

Series

**8310**

Type

**2**

2 B Female

Layout

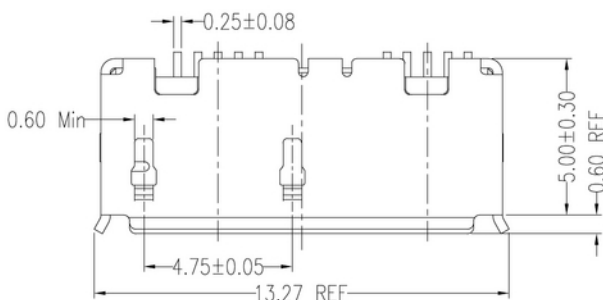
**2**

2 Liegend  
Horizontal

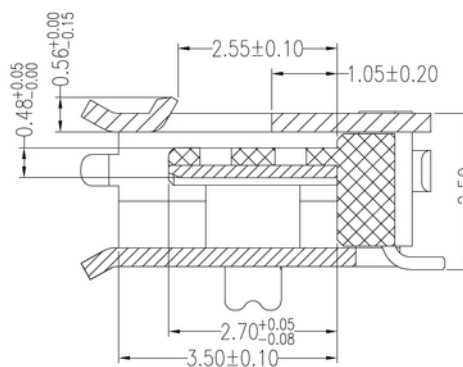
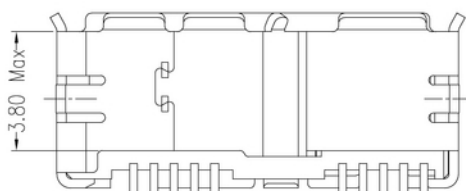
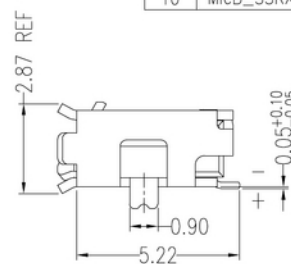
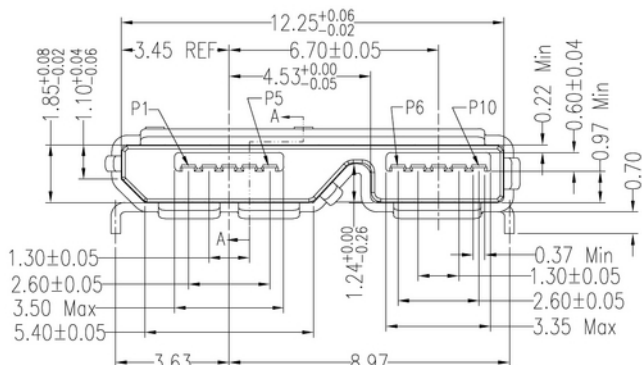
Plating

**80**

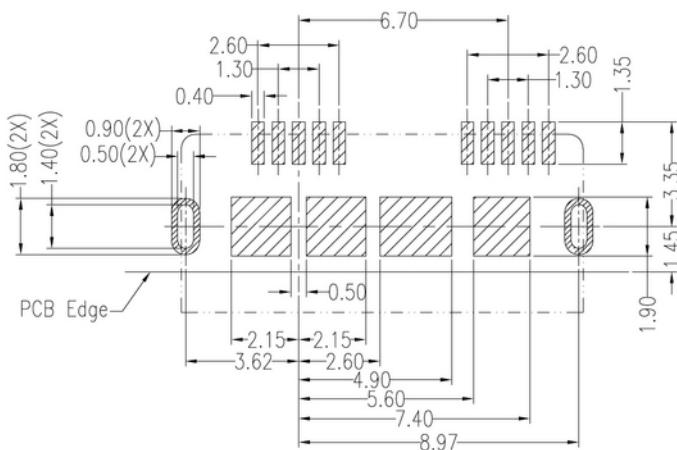
80 Sel. Au 0,75µm/Sn



Pin Number	Signal Name
1	VBUS
2	D-
3	D+
4	ID
5	GND
6	MicB_SSTX-
7	MicB_SSTX+
8	GND_DRAIN
9	MicB_SSRX-
10	MicB_SSRX+



SECTION: A-A  
SCALE: 2:1



RECOMMENDED PCB LAYOUT  
COMPONENT SIDE (Tol: ±0.05)

Series

**8310**

Type

**2**

2 B Female

Layout

**5**

5 Liegend mit Lötflanschen  
Horizontal with solder latches

Plating

**80**

80 Sel. Au 0,75µm/Sn

# Informationen zum Reflow-Lötverfahren

## Reflow Soldering Information

### Reflow-Lötempfehlung

#### Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150°C
Temperatur Maximum $T_{Smax}$	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich $T_L$	217°C
Verweildauer oberhalb $T_L$	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur $T_P$	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur $T_P$	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150°C
Maximum Temperatur $T_{Smax}$	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature $T_L$	217°C
Duration above $T_L$	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature $T_P$	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. $T_P$	Max. 8min

